

NOTES:

1. PLACE ALL PARTS ON A 0, 45, OR 90 DEGREE ORIENTATION.
2. DIFFERENTIAL NETS ARE: TDP/N, TDP_DINP/N, MODP/N, TD_DATA_P/N, RDP/N, RD_DINP/N, RD_DATAP/N
3. DIFFERENTIAL DATA SHOULD BE ROUTED AS 100 OHM TRANSMISSION LINES ON OUTSIDE LAYERS UNLESS SPECIFIED
4. MODP/N AND TD_DATA_P/N SHOULD BE ROUTED AS 25 OHM TRANSMISSION LINE ON OUTSIDE LAYERS
5. DIFFERENTIAL NETS MUST MATCH WITHIN +/- 0.5 MILS
6. USE FR4-370 MATERIAL FOR ALL LAYERS.
7. STACKUP SHOULD BE TOP SIGNAL, L2 GND, L3 PWR, BOTTOM SIGNAL

REVISIONS

ECR	ECR NUMBER	DATE
	-----	xx/xx/xx

SCHEMATIC SHEET INDEX:

- SHEET 01: COVER SHEET AND NOTES
 SHEET 02: SCHEMATIC



TEXAS INSTRUMENTS

SCHEMATIC TITLE
 ONET1151P/L 10G SFP+
 REFERENCE DESIGN

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J. NERGER	08/19/13
LAYOUT	DATE
DFW TEST	08/19/13
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 COVER PAGE AND NOTES

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